



August 1, 2024

[Product Information Notification \(PIN\): Endpoint IC Wafer Label Standardization](#)

Products affected:

- Impinj Monza 4D, 4E, 4QT
- Impinj Monza R6, R6-P
- Impinj M730, M750, M770, M775, M780, M781
- Impinj M830, M850

As part of our continuous improvement efforts, Impinj is standardizing the labeling of our 200mm and 300mm endpoint IC wafer products. Effective immediately, all newly manufactured wafers will have a white label on the carrier frame with printed information including wafer ID, mount date, and cure date. The printed label replaces handwritten information that appeared on previous wafers between the wafer edge and the carrier frame.

Until previous inventory is exhausted, you may receive wafers with either a printed label or handwritten information.

If you have questions or need assistance, please contact your Impinj account manager or the Impinj support team at support@impinj.com.

Thank you,

Martin Liebl
Senior Product Management Director, Tag ICs